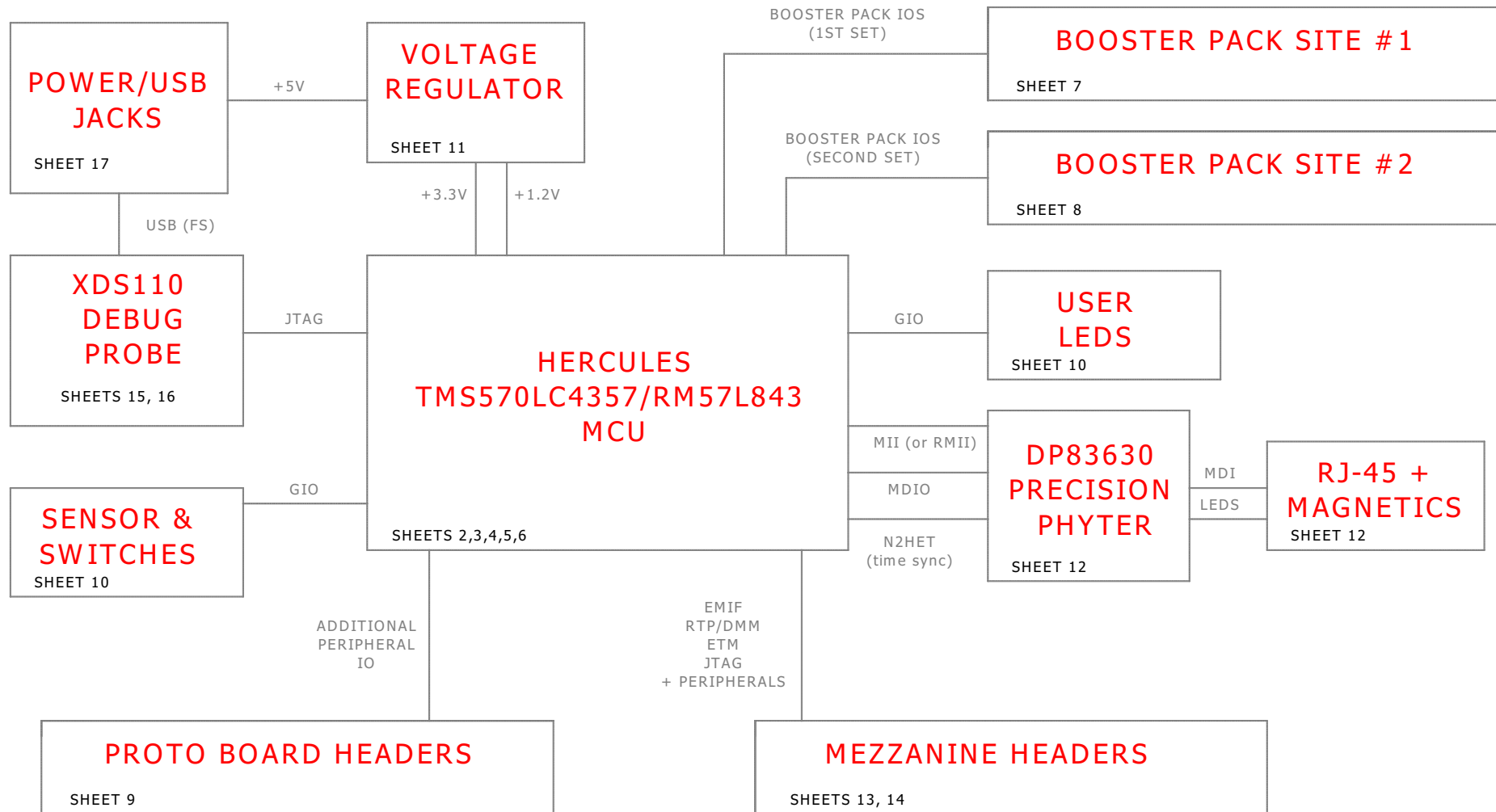


LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L

337 ZWT LAUNCHPAD XL2



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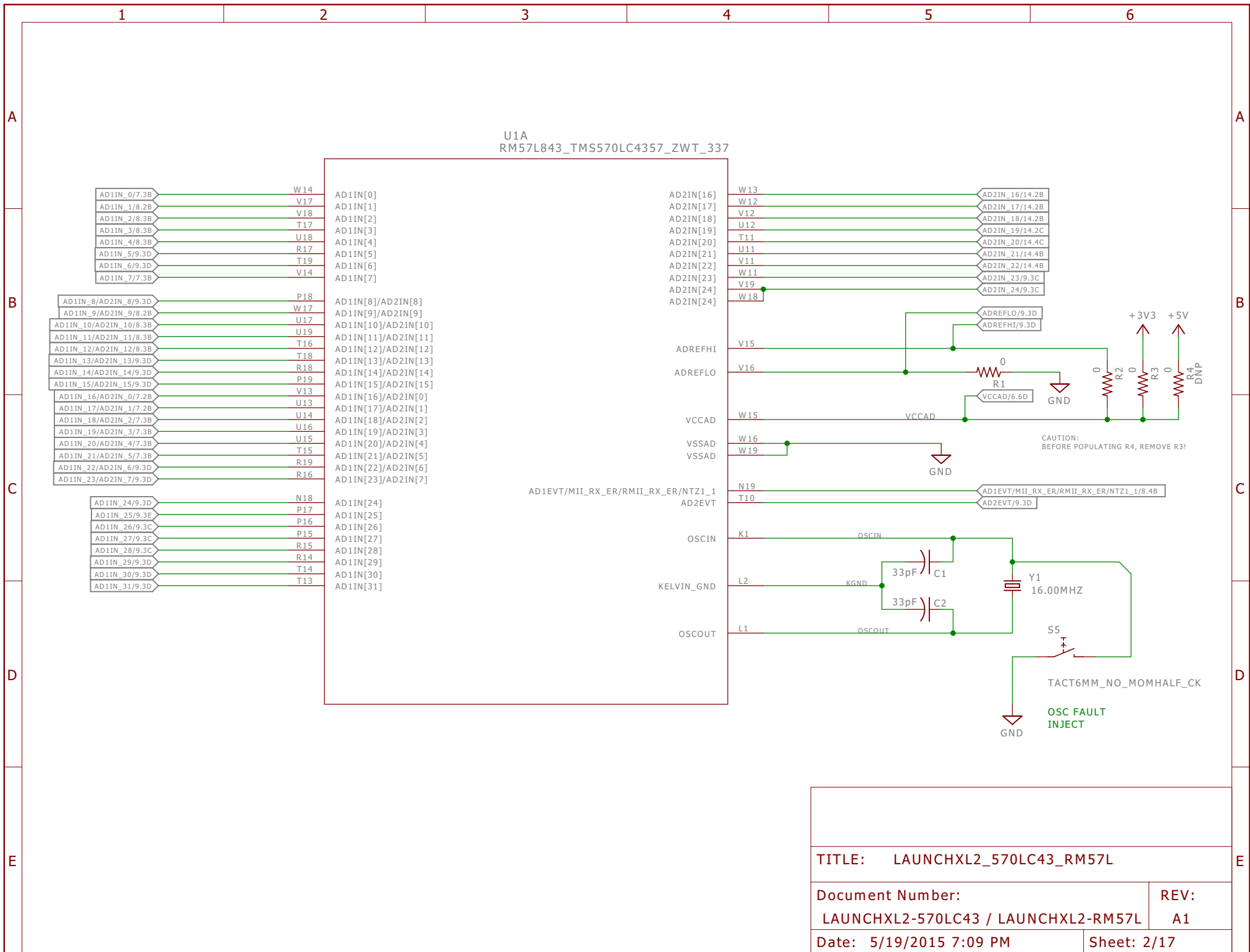
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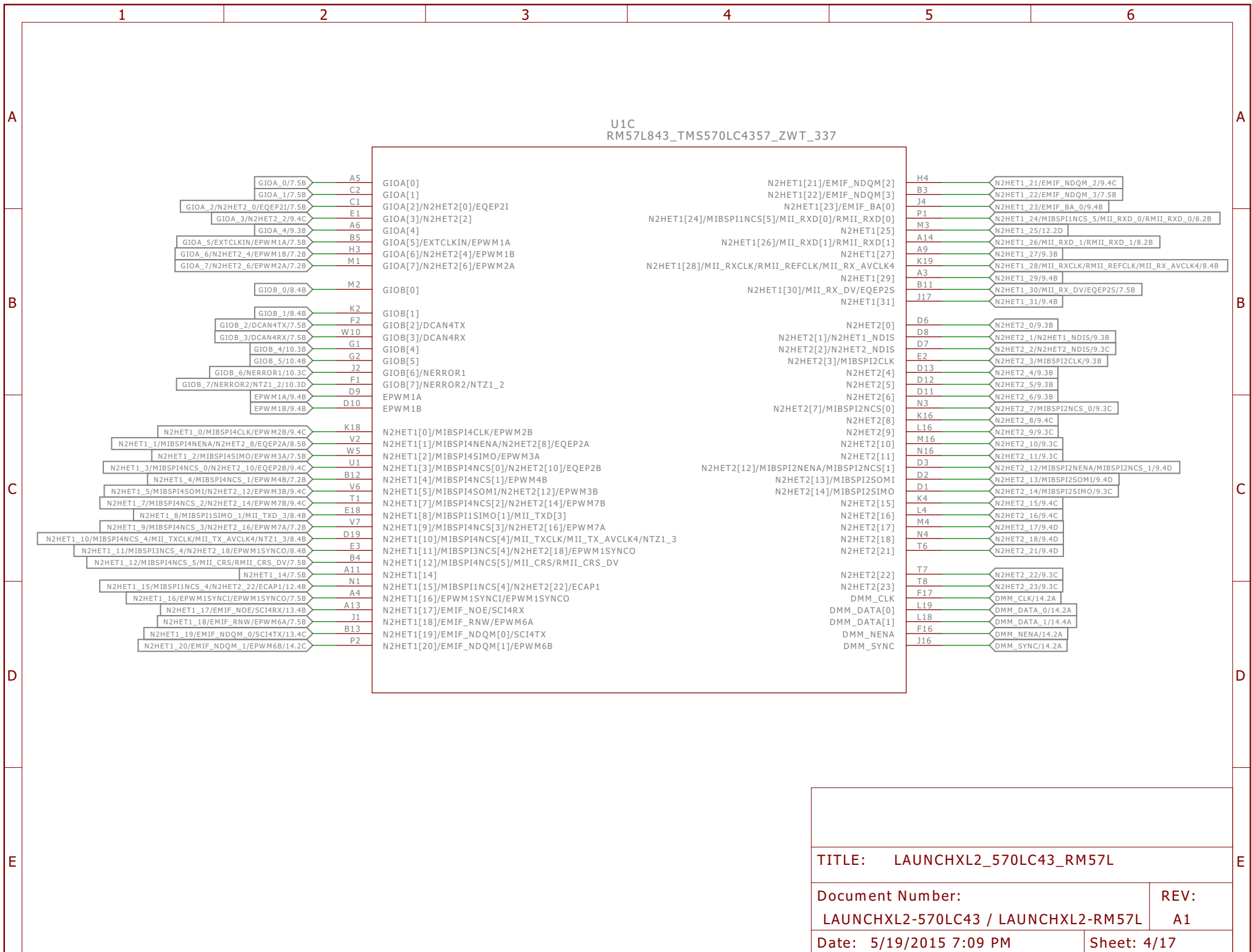
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A1

Date: 5/19/2015 7:09 PM

Sheet: 1/17





GIOB_0/8.4B

GIOB_1/8.4B

GIOB_2/DCAN4TX/7.5B

GIOB_3/DCAN4RX/7.5B

GIOB_4/10.3B

GIOB_5/10.4B

GIOB_6/NERROR1/10.3C

GIOB_7/NERROR2/NTZ1_2/10.3D

EPWM1A/9.4B

EPWM1B/9.4B

K18

V2

W5

U1

B12

V6

T1

E18

V7

D19

E3

B4

A11

N1

A4

A13

J1

B13

P2

GIOB[0]

GIOB[1]

GIOB[2]/DCAN4TX

GIOB[3]/DCAN4RX

GIOB[4]

GIOB[5]

GIOB[6]/NERROR1

GIOB[7]/NERROR2/NTZ1_2

EPWM1A

EPWM1B

N2HET1[0]/MIBSPI4CLK/EPWM2B

N2HET1[1]/MIBSPI4NENA/N2HET2[8]/EQEP2A

N2HET1[2]/MIBSPI4SIMO/EPWM3A

N2HET1[3]/MIBSPI4NCS[0]/N2HET2[10]/EQEP2B

N2HET1[4]/MIBSPI4NCS[1]/EPWM4B

N2HET1[5]/MIBSPI4SOMI/N2HET2[12]/EPWM3B

N2HET1[7]/MIBSPI4NCS[2]/N2HET2[14]/EPWM7B

N2HET1[8]/MIBSPI1SIMO[1]/MII_TXD[3]

N2HET1[9]/MIBSPI4NCS[3]/N2HET2[16]/EPWM7A

N2HET1[10]/MIBSPI4NCS[4]/MII_TXCLK/MII_TX_AVCLK4/NTZ1_3

N2HET1[11]/MIBSPI3NCS[4]/N2HET2[18]/EPWM1SYNCO

N2HET1[12]/MIBSPI4NCS[5]/MII_CRS/RMII_CRS_DV

N2HET1[14]

N2HET1[15]/MIBSPI1NCS[4]/N2HET2[22]/ECAP1

N2HET1[16]/EPWM1SYNCI/EPWM1SYNCO

N2HET1[17]/EMIF_NOE/SCI4RX

N2HET1[18]/EMIF_RNW/EPWM6A

N2HET1[19]/EMIF_NDQM[0]/SCI4TX

N2HET1[20]/EMIF_NDQM[1]/EPWM6B

N2HET1[21]/EMIF_NDQM[2]

N2HET1[22]/EMIF_NDQM[3]

N2HET1[23]/EMIF_BA[0]

N2HET1[24]/MIBSPI1NCS[5]/MII_RXD[0]/RMII_RXD[0]

N2HET1[25]

N2HET1[26]/MII_RXD[1]/RMII_RXD[1]

N2HET1[27]

N2HET1[29]

N2HET1[30]/MII_RX_DV/EQEP2S

N2HET1[31]

N2HET2[0]

N2HET2[1]/N2HET1_NDIS

N2HET2[2]/N2HET2_NDIS

N2HET2[3]/MIBSPI2CLK

N2HET2[4]

N2HET2[5]

N2HET2[6]

N2HET2[7]/MIBSPI2NCS[0]

N2HET2[8]

N2HET2[9]

N2HET2[10]

N2HET2[11]

N2HET2[12]/MIBSPI2NENA/MIBSPI2NCS[1]

N2HET2[13]/MIBSPI2SOMI

N2HET2[14]/MIBSPI2SIMO

N2HET2[15]

N2HET2[16]

N2HET2[17]

N2HET2[18]

N2HET2[21]

N2HET2[22]

N2HET2[23]

DMM_CLK

DMM_DATA[0]

DMM_DATA[1]

DMM_NENA

DMM_SYNC

H4

B3

J4

P1

M3

A14

A9

K19

A3

B11

J17

D6

D8

D7

E2

D13

D12

D11

N3

K16

L16

M16

N16

D3

D2

D1

K4

L4

M4

N4

T6

T7

T8

F17

L19

L18

F16

J16

N2HET1_21/EMIF_NDQM_2/9.4C

N2HET1_22/EMIF_NDQM_3/7.5B

N2HET1_23/EMIF_BA_0/9.4B

N2HET1_24/MIBSPI1NCS_5/MII_RXD_0/RMII_RXD_0/8.2B

N2HET1_25/12.2D

N2HET1_26/MII_RXD_1/RMII_RXD_1/8.2B

N2HET1_27/9.3B

N2HET1_28/MII_RXCLK/RMII_REFCLK/MII_RX_AVCLK4/8.4B

N2HET1_29/9.4B

N2HET1_30/MII_RX_DV/EQEP2S/7.5B

N2HET1_31/9.4B

N2HET2_0/9.3B

N2HET2_1/N2HET1_NDIS/9.3B

N2HET2_2/N2HET2_NDIS/9.3C

N2HET2_3/MIBSPI2CLK/9.3B

N2HET2_4/9.3B

N2HET2_5/9.3B

N2HET2_6/9.3B

N2HET2_7/MIBSPI2NCS_0/9.3C

N2HET2_8/9.4C

N2HET2_9/9.3C

N2HET2_10/9.3C

N2HET2_11/9.3C

N2HET2_12/MIBSPI2NENA/MIBSPI2NCS_1/9.4D

N2HET2_13/MIBSPI2SOMI/9.4D

N2HET2_14/MIBSPI2SIMO/9.3C

N2HET2_15/9.4C

N2HET2_16/9.4C

N2HET2_17/9.4D

N2HET2_18/9.4D

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N2HET2_23/9.3C

DMM_CLK/14.2A

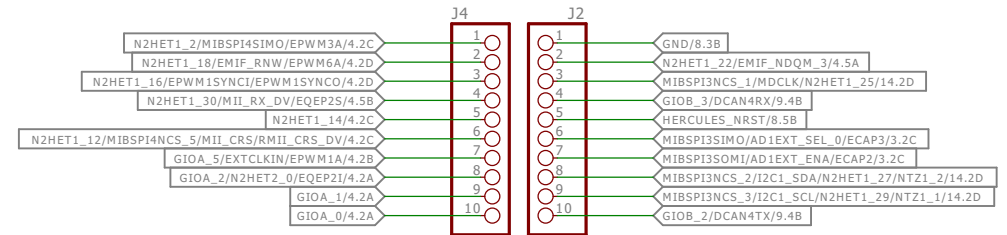
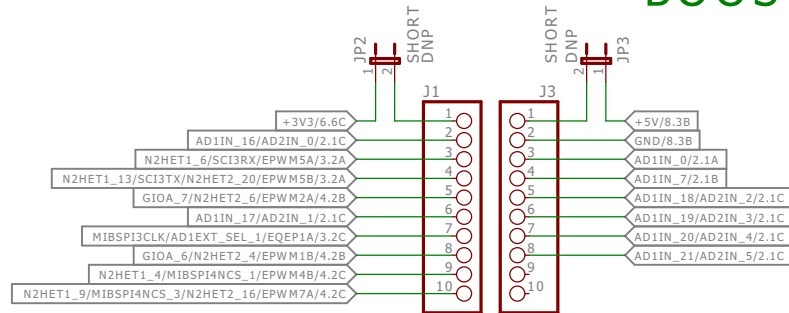
DMM_DATA_0/14.2A

DMM_DATA_1/14.4A

DMM_NENA/14.2A

DMM_SYNC/14.2A

BOOSTER PACK SITE 1



Headers/Receptacles may be ordered from <http://launchpad.mlelectronics.com/>

NOTES:

JP2 & JP3 are normally shorted on the PCB - the footprint consists of an (unpopulated) 2 pin SMT header and a solder-bridging structure. Most users can leave these jumpers as-is.

Certain booster packs may require that the position is opened - these are booster packs that would otherwise supply power to the launchpad through these pins. Providing +3V3 to the launchpad is a problem because there would be a conflict with the launchpad's on-board LM26420 regulator. Providing +5V to the launchpad through the booster pack could be ok, but the barrel jack is preferred as it is protected with a PTC. Also be careful to avoid back powering the USB connection if you do this.

In some cases you may find the need to make/break the connections JP2,JP3 frequently. If you do, then you can remove the solder bridge and mount a 2 pin SMT header on the footprint location which can then be opened/closed by using a Jumper or Shunt.

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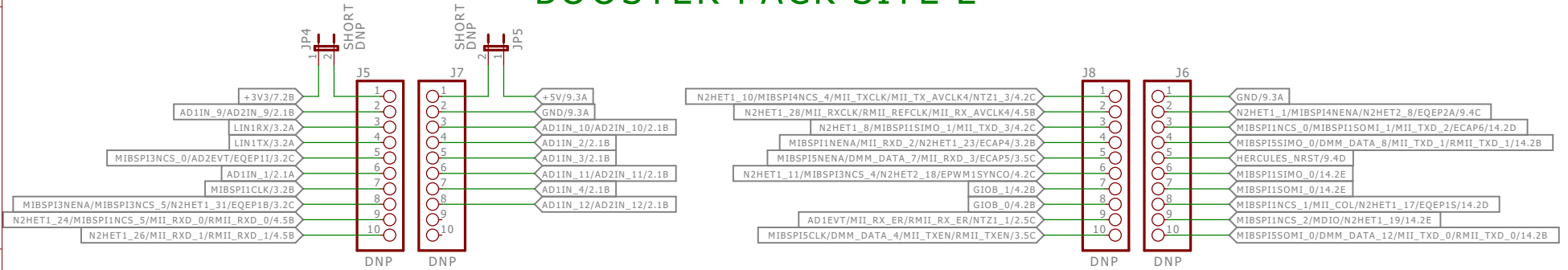
Document Number:
LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L

REV:
A1

Date: 5/19/2015 7:09 PM

Sheet: 7/17

BOOSTER PACK SITE 2



Headers/Receptacles may be ordered from <http://launchpad.mlelectronics.com/>

NOTES:

JP4 & JP5 are normally shorted on the PCB - the footprint consists of an (unpopulated) 2 pin SMT header and a solder-bridging structure. Most users can leave these jumpers as-is.

Certain booster packs may require that the position is opened - these are booster packs that would otherwise supply power to the launchpad through these pins. Providing +3V3 to the launchpad is a problem because there would be a conflict with the launchpad's on-board LM26420 regulator. Providing +5V to the launchpad through the booster pack could be ok, but the barrel jack is preferred as it is protected with a PTC. Also be careful to avoid back powering the USB connection if you do this.

In some cases you may find the need to make/break the connections JP4,JP5 frequently. If you do, then you can remove the solder bridge and mount a 2 pin SMT header on the footprint location which can then be opened/closed by using a Jumper or Shunt.

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LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L

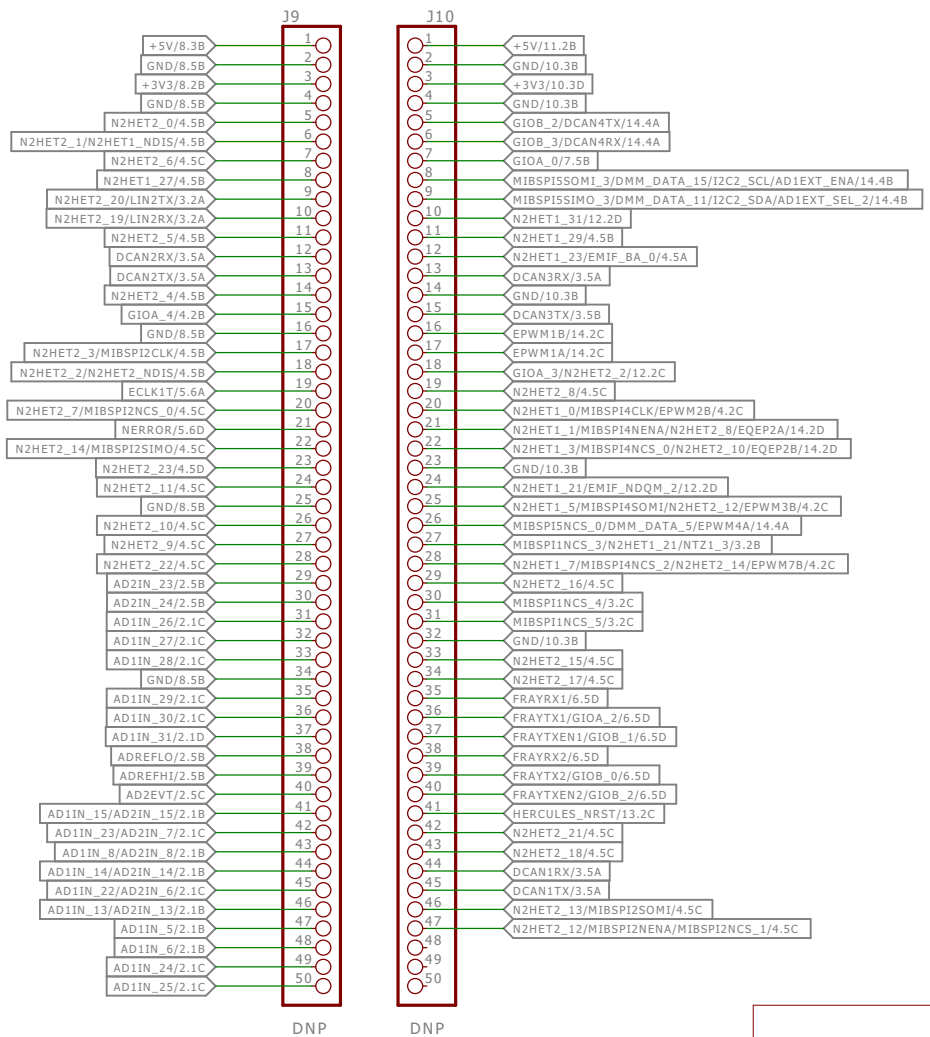
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A1

Date: 5/19/2015 7:09 PM

Sheet: 8/17

PROTO BOARD HEADERS



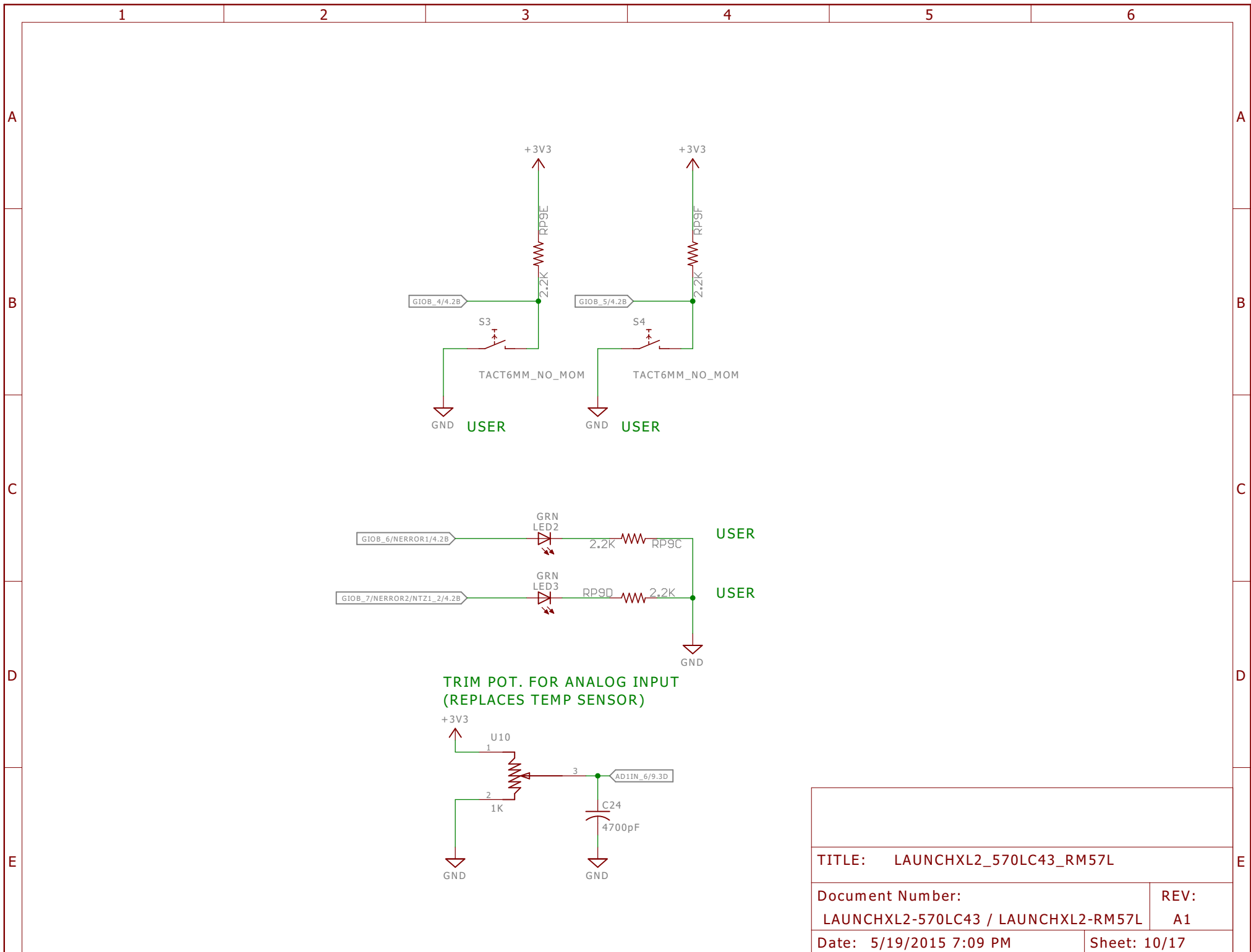
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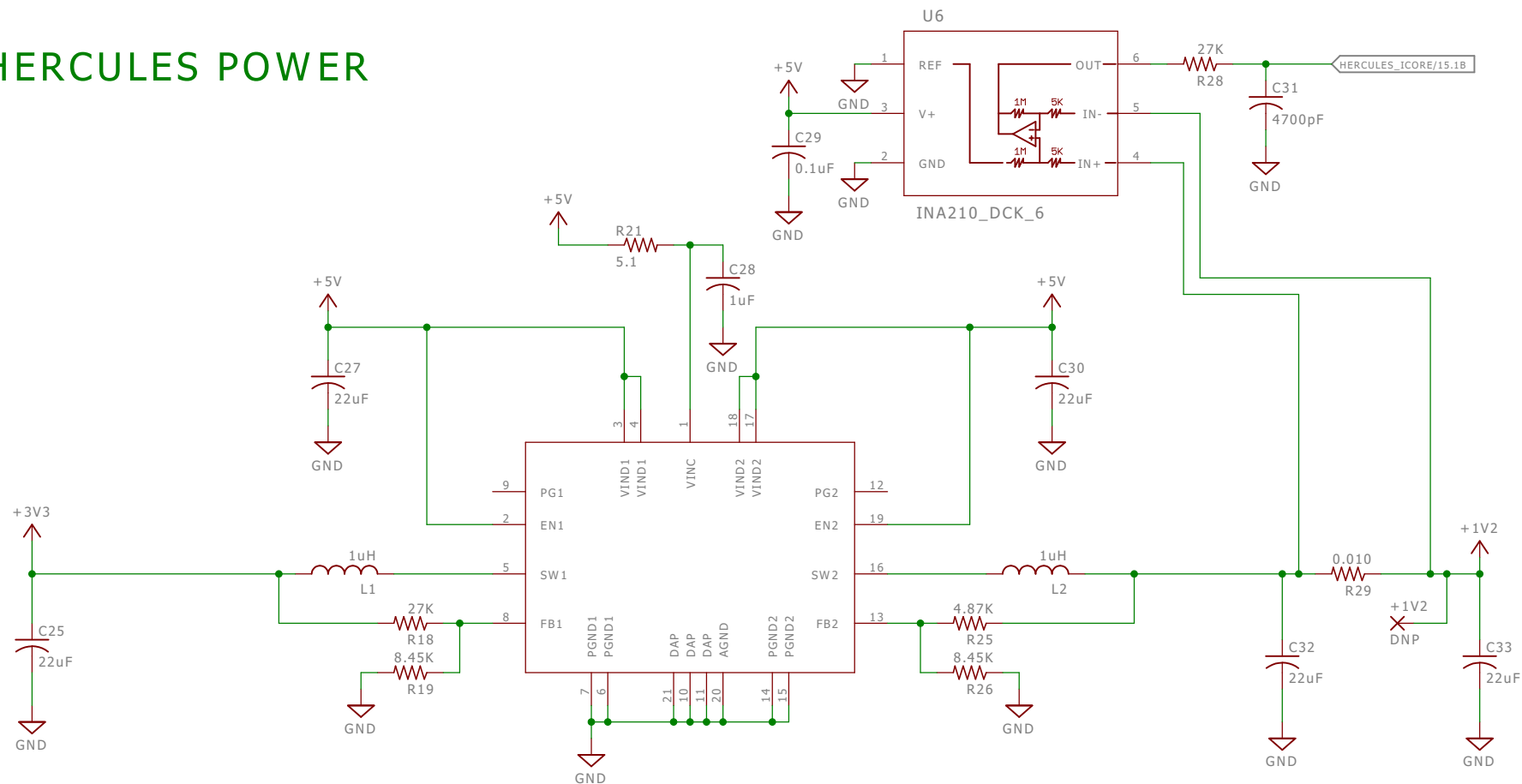
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Date: 5/19/2015 7:09 PM

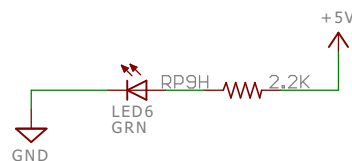
Sheet: 9/17



HERCULES POWER



POWER INDICATOR LED



+5V

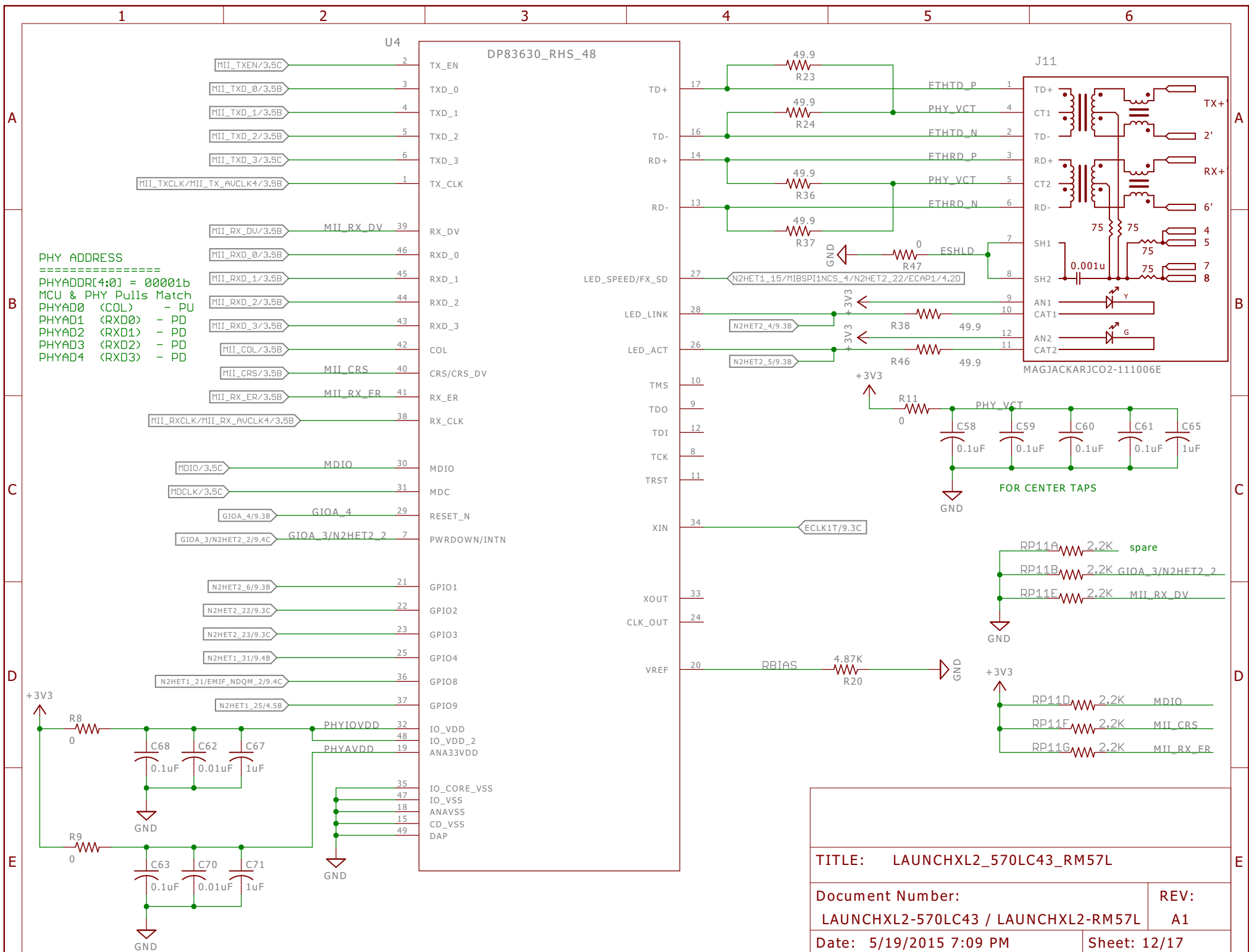
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Document Number:
LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L

REV:
A1

Date: 5/19/2015 7:09 PM

Sheet: 11/17



TITLE: LAUNCHXL2_570LC43_RM57L

Document Number:
 LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L

REV:
 A1

Date: 5/19/2015 7:09 PM

Sheet: 12/17

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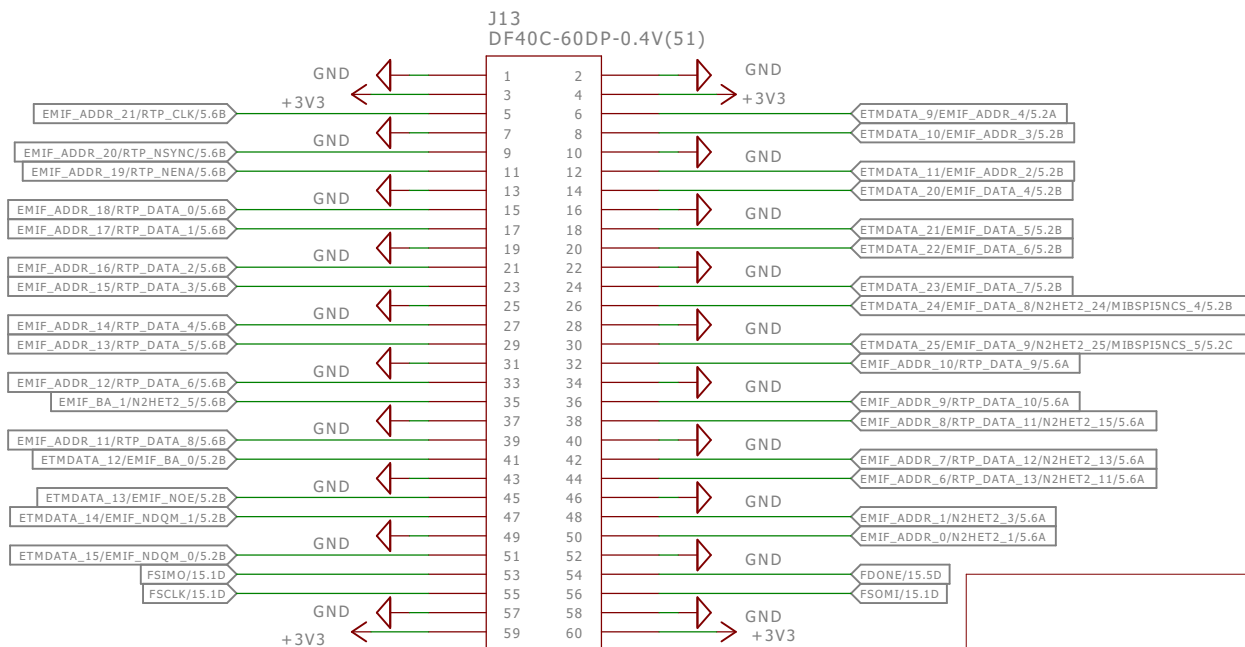
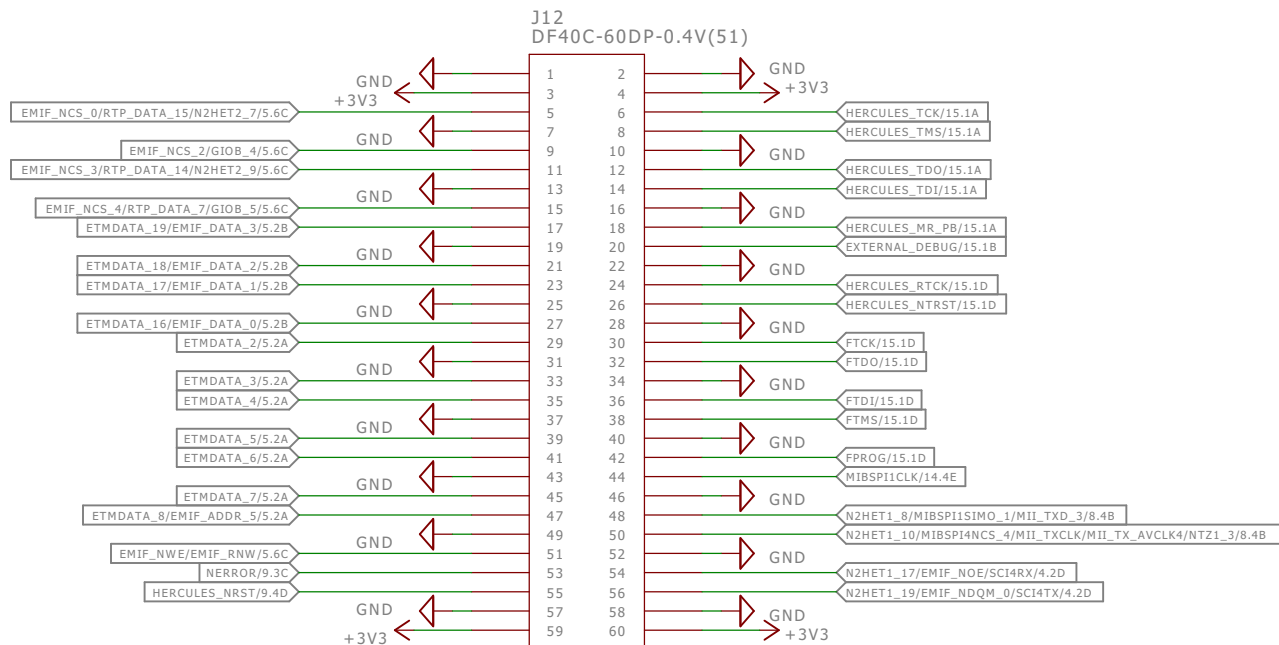
A

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Document Number:

LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L

REV:

A1

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Sheet: 13/17

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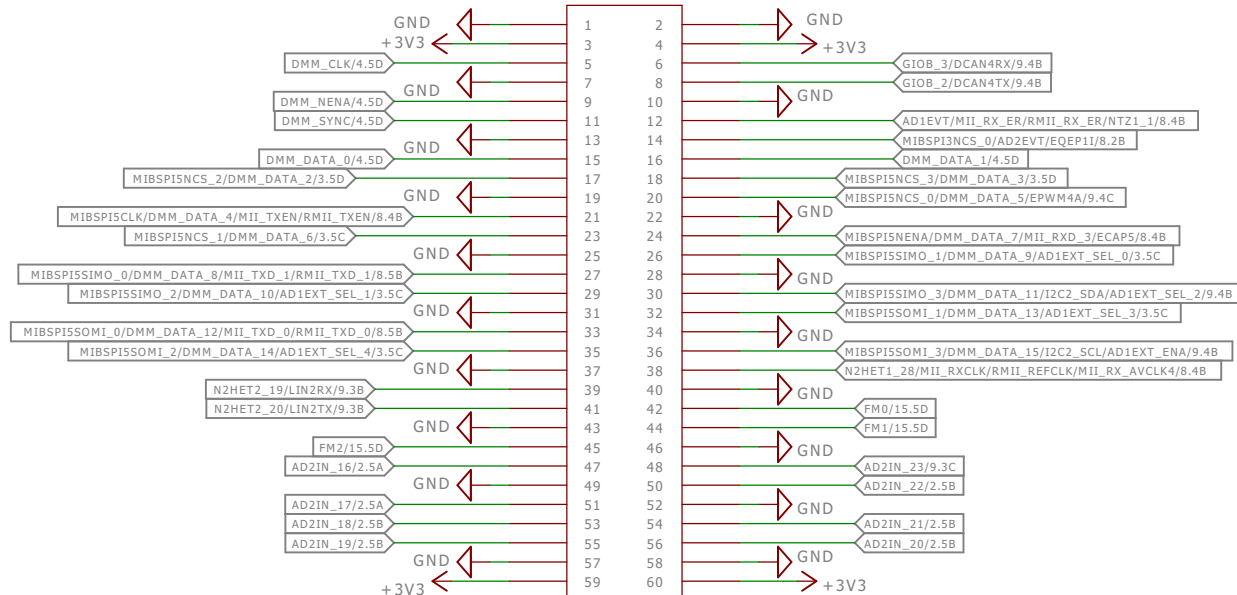
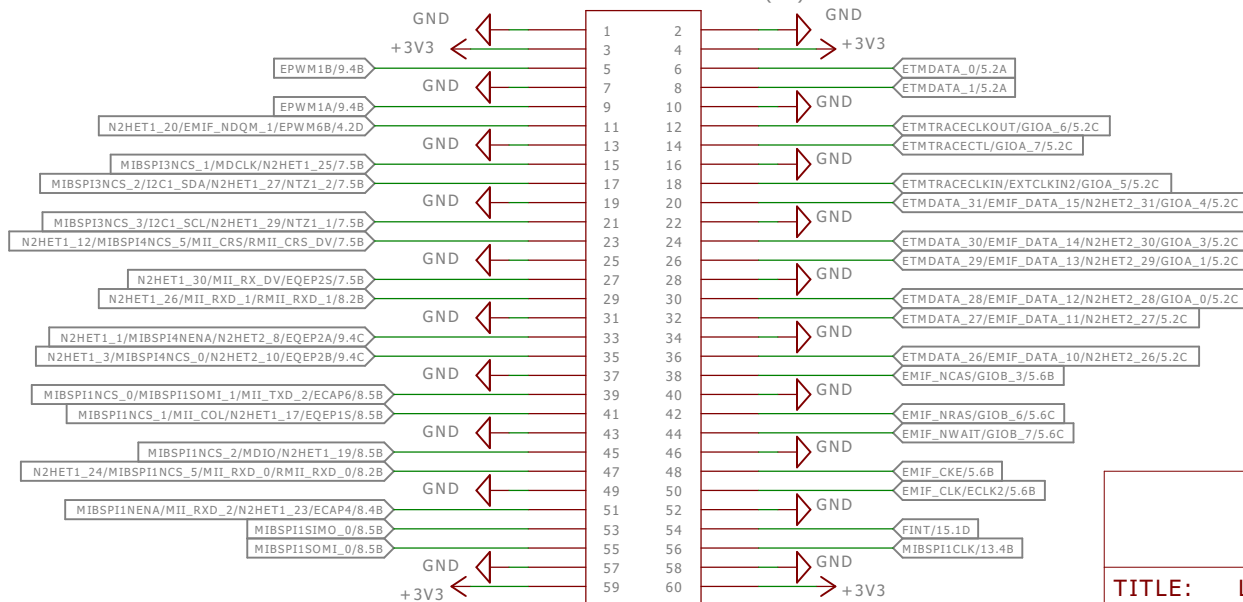
A

B

C

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J14
DF40C-60DP-0.4V(51)J15
DF40C-60DP-0.4V(51)

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LAUNCHXL2-570LC43 / LAUNCHXL2-RM57LREV:
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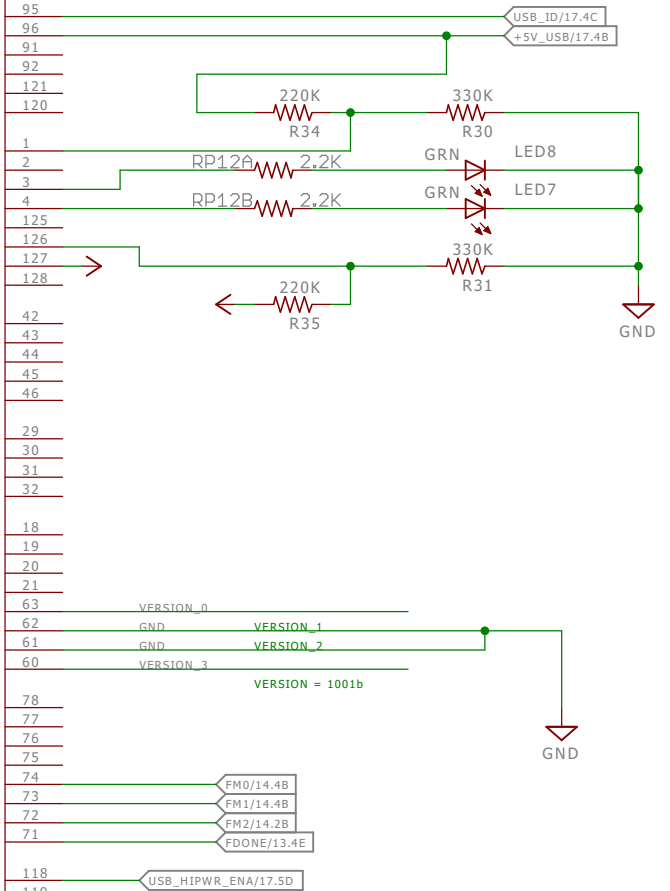
Date: 5/19/2015 7:09 PM

Sheet: 14/17

XDS110 DEBUG PROBE

U7A

TM4C129ENCPDT



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LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L

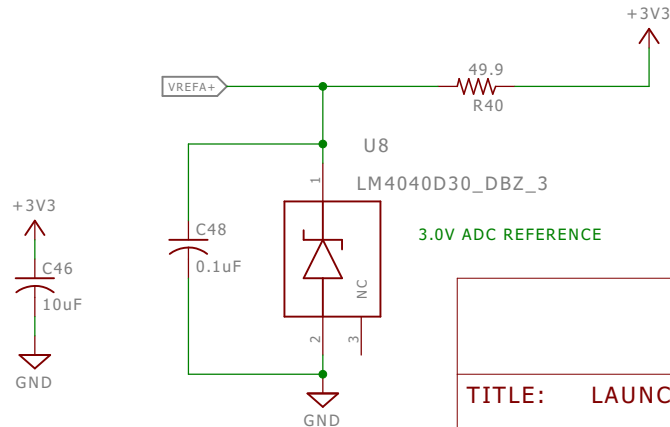
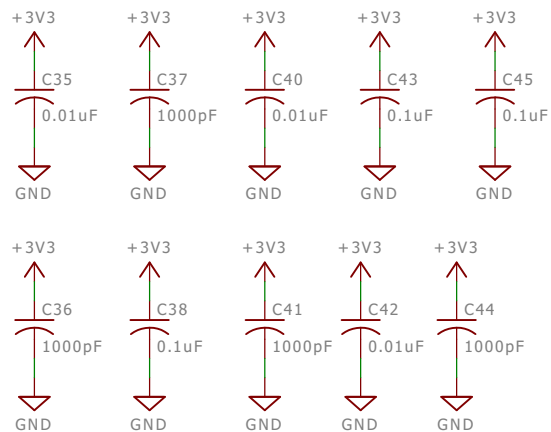
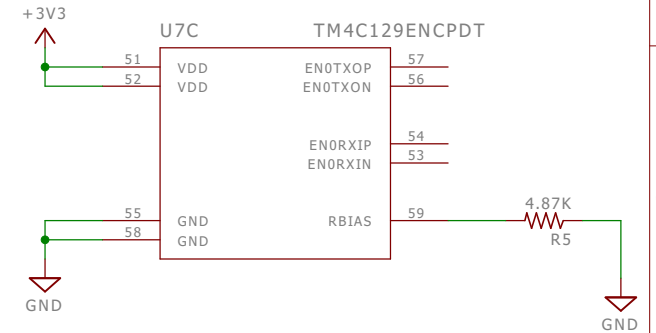
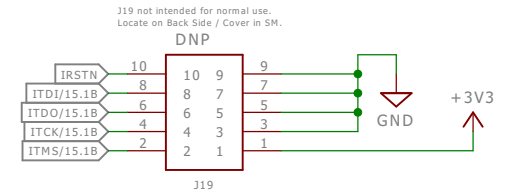
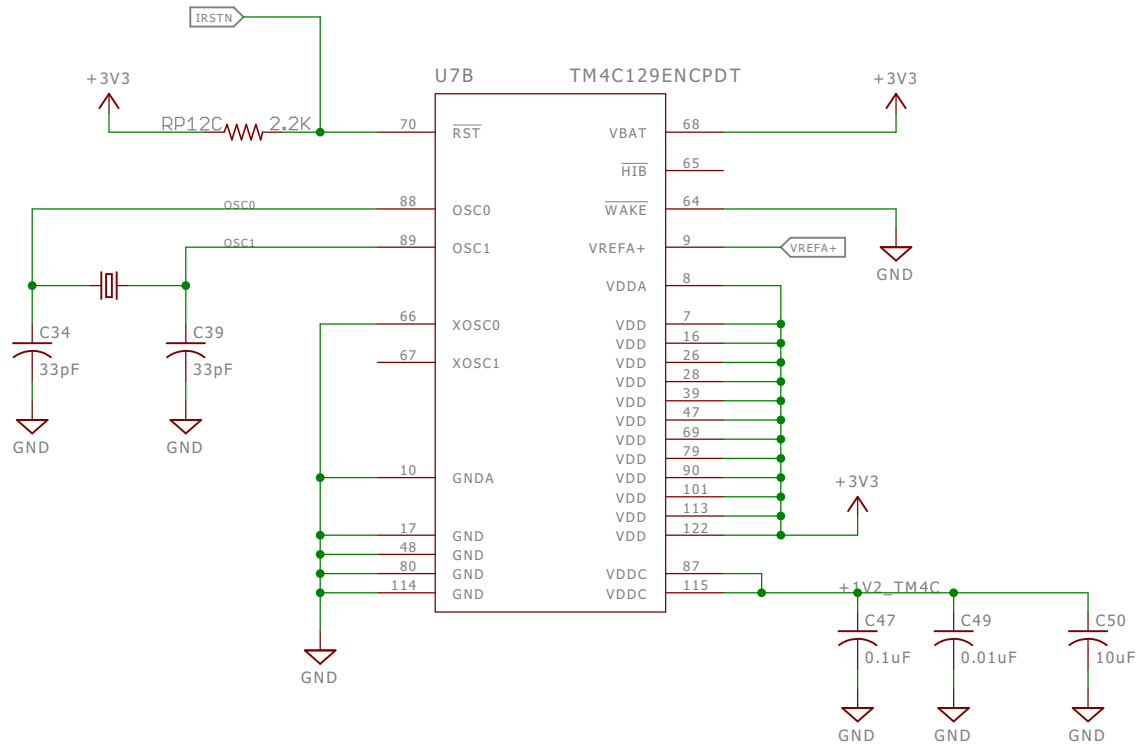
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Date: 5/19/2015 7:09 PM

Sheet: 15/17

XDS110 DEBUG PROBE



TITLE: LAUNCHXL2_570LC43_RM57L

Document Number:

LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L

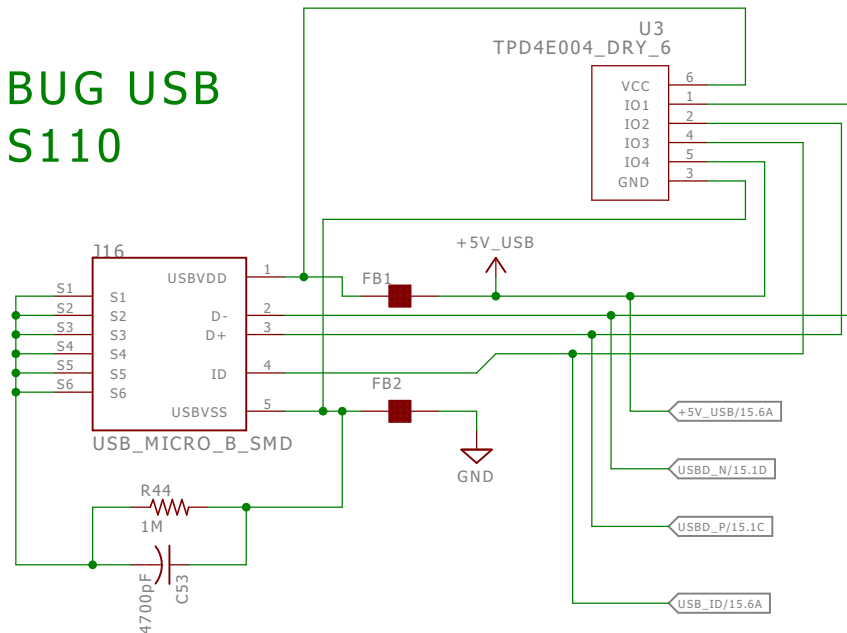
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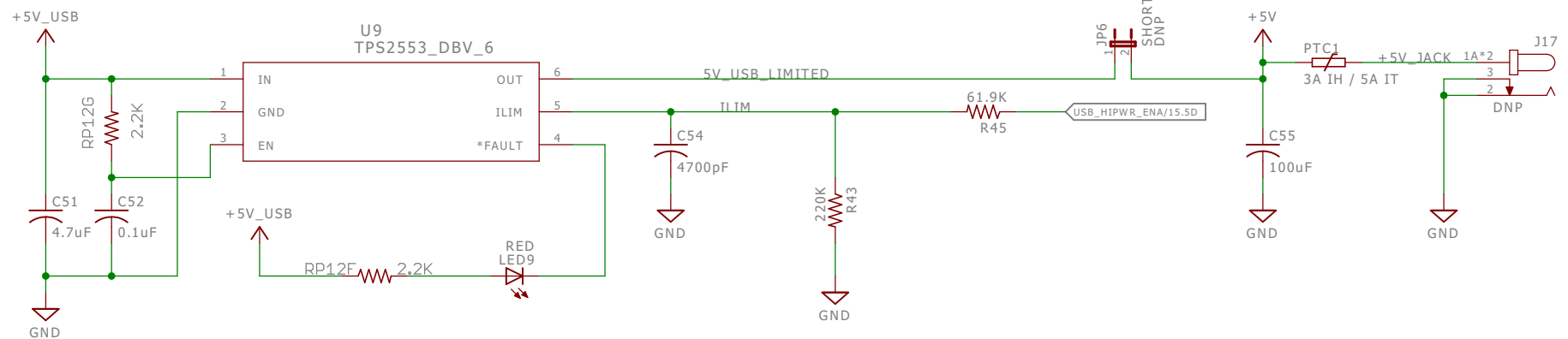
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Sheet: 16/17

DEBUG USB XDS110

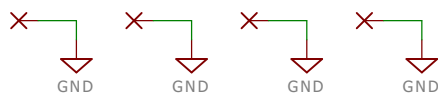


CURRENT LIMITING FOR BUS POWERED OPERATION



REMOVE JUMPER TO POWER THROUGH BARREL JACK

GND POINTS



FIDUCIALS



MNT HOLES



TITLE: LAUNCHXL2_570LC43_RM57L

Document Number:
LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L

REV:
A1

Date: 5/19/2015 7:09 PM

Sheet: 17/17

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